

Advances in technologies for power exhaust solutions

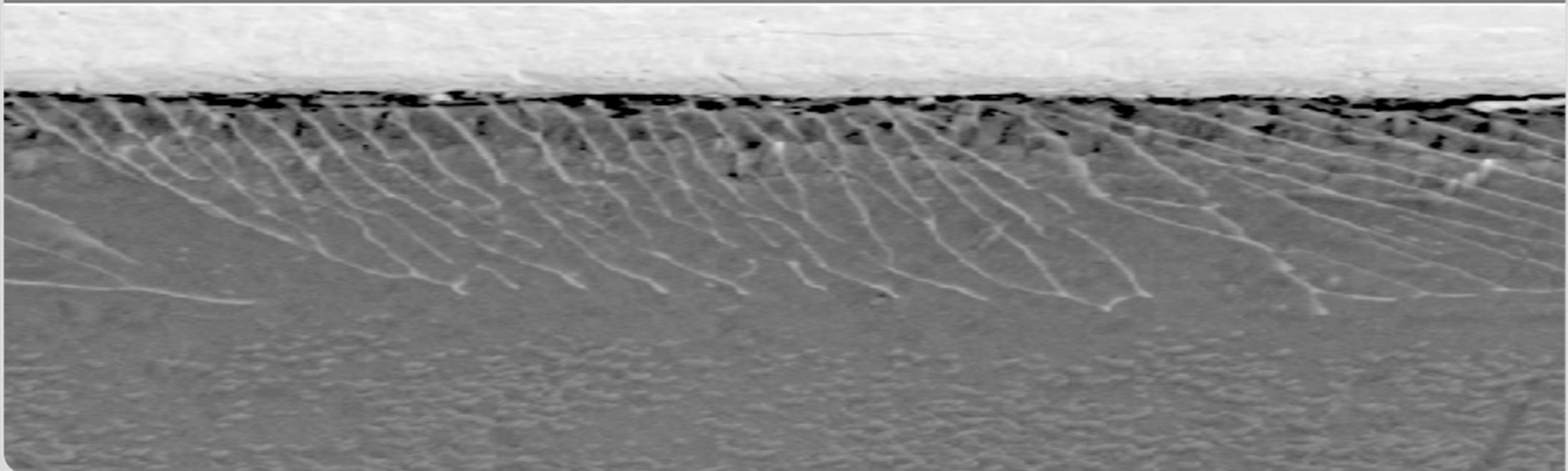
J. Reiser¹, M. Rieth¹, A. Möslang¹, A. Hoffmann²

¹ Karlsruhe Institute of Technology, Institute for Applied Materials, Germany

² PLANSEE SE, Reutte, Austria

XXI Conference, Italian Association of Science and Technology, 15-17 May, Catania

INSTITUTE FOR APPLIED MATERIALS, APPLIED MATERIALS PHYSICS



Contents

- Electrical industry
 - How to remove high heat fluxes in electrical industry?

- Fusion applications
 - How to remove the heat flux in Tore Supra, W7-X and ITER

- Ductilisation of tungsten (W)
 - Alloying, composite material, UFG
 - W-laminates made of W-foil (UFG)

- W-laminates for high heat flux applications

Summary of heat fluxes

Sun, beach



Rocket nozzle



NASA

Solar tower



ABENGOA Solar

Electrical ind.



PLANSEE SE

0,001 MW/m²

3 MW/m²

6 MW/m²

50 MW/m²

Fusion:
Divertor 20 MW/m²

What can we learn from electrical industry?

Request

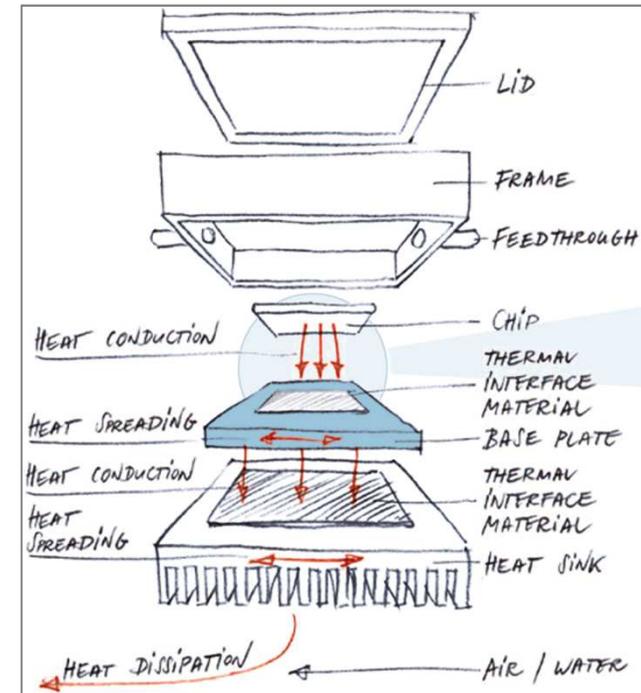
- heat load: 0,5 – 50 MW/m²
- Max. temp.: 150°C

Solution

- MoCu materials
 - Cu: high thermal conductivity, k
 - Mo: low coefficient of therm. exp., α

Applications

- Radar applications
- High power LEDs
- ...



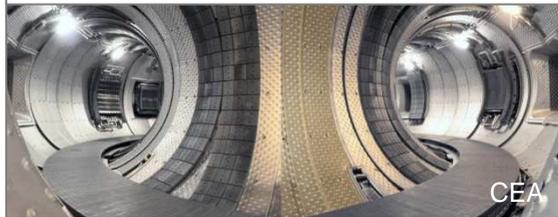
PLANSEE SE



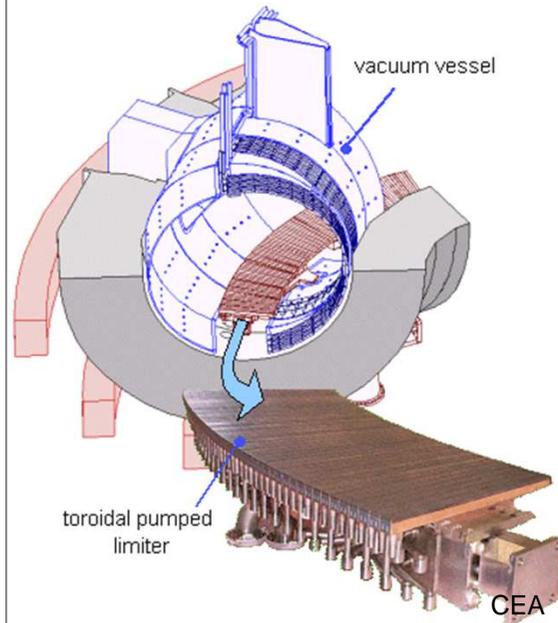
PLANSEE SE

Heat load and fusion

Tore Supra, tokamak, limiter

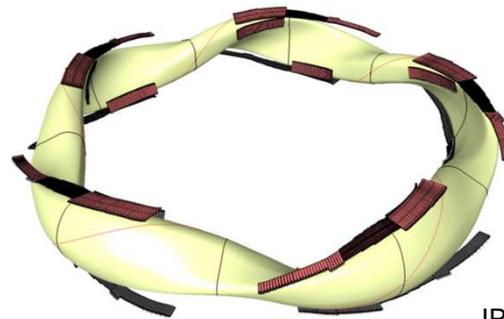


CEA



CEA

W7-X, stellerator, divertor

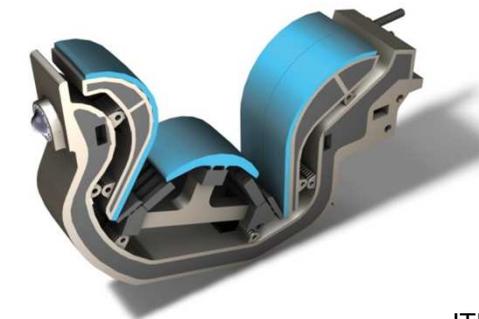
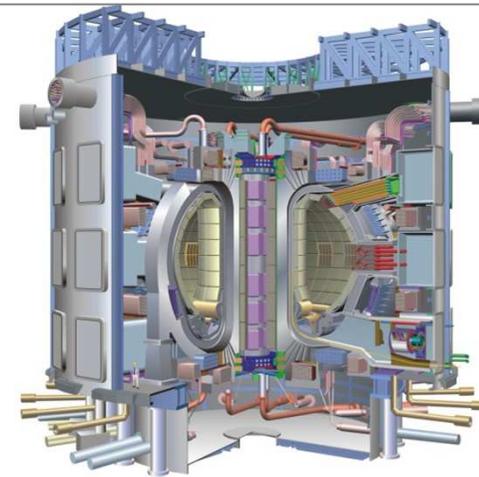


IPP



IPP

ITER, tokamak, divertor



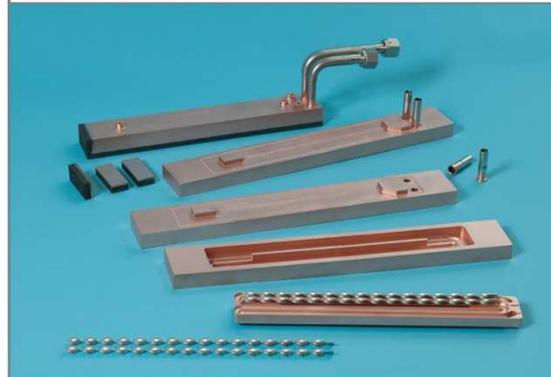
ITER

Heat load and fusion

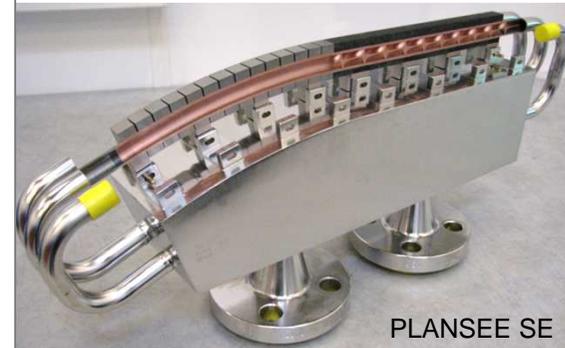
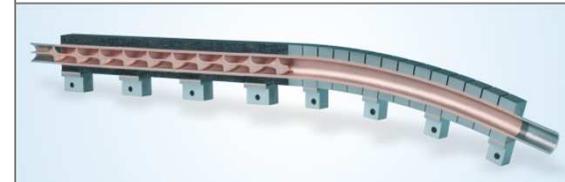
Tore Supra, tokamak,
limiter



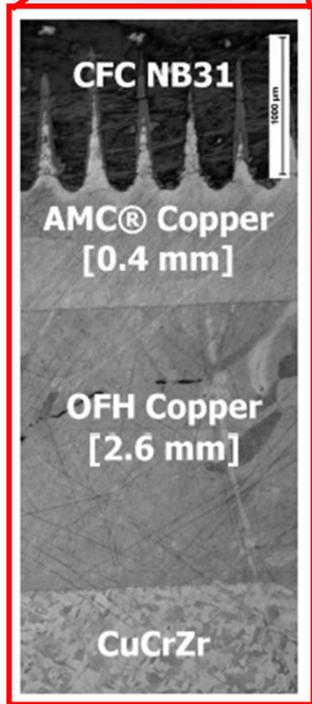
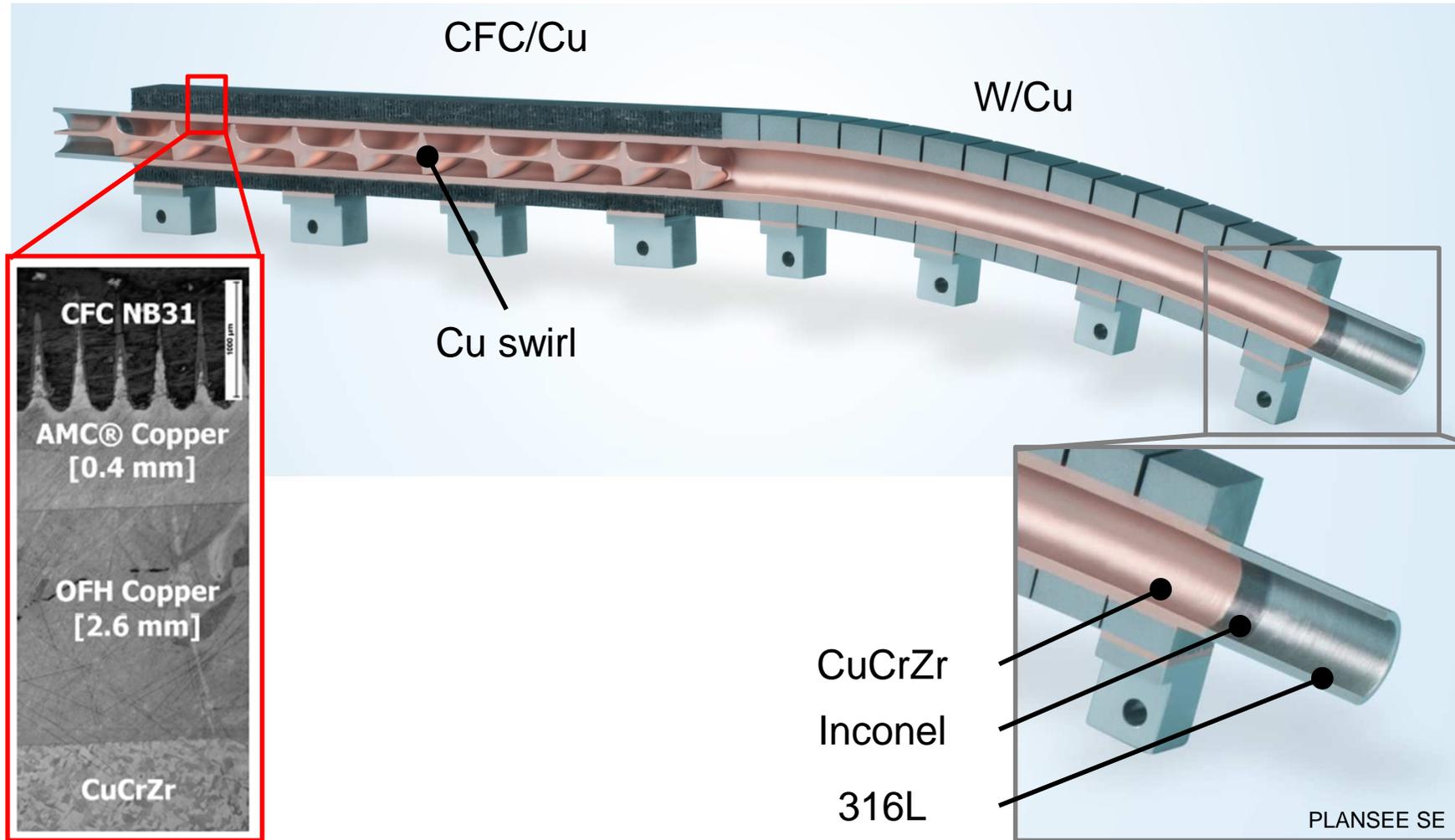
W7-X, stellerator,
divertor



ITER, tokamak, divertor



Fabrication technology

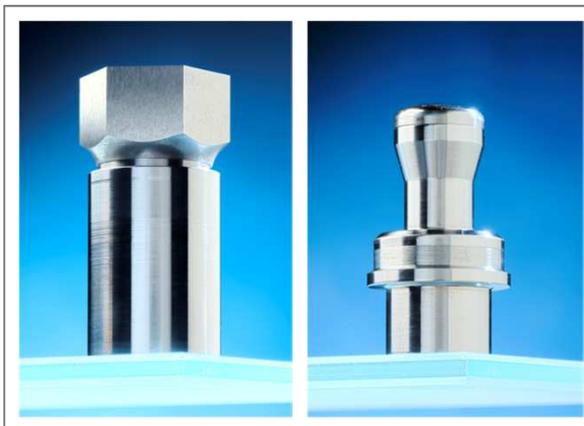


Boscary, 2009

Helium-cooled divertor and tungsten (W)

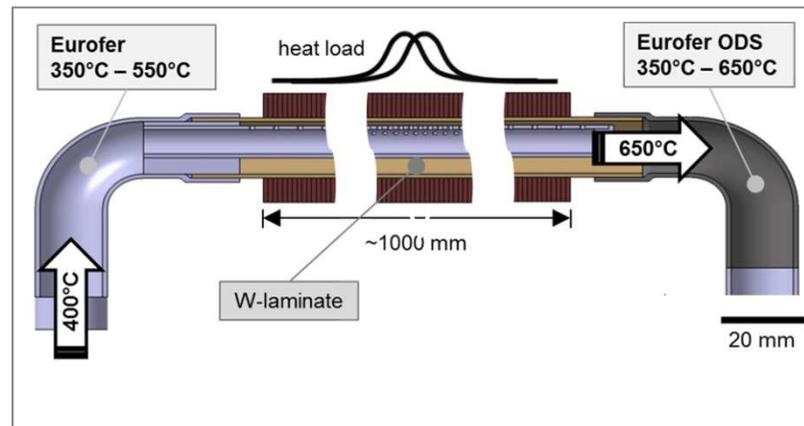
- Most of the He-cooled divertor concepts ask for tungsten as a structural material
- Requirement:
 - High fracture toughness, K_{IC} [MPa(m)^{1/2}]
 - Low brittle-to-ductile transition temperature (BDTT) measured by Charpy
 - Operation conditions: 100 bar, $T = 600^{\circ}\text{C} - 800^{\circ}\text{C}$

Finger concept



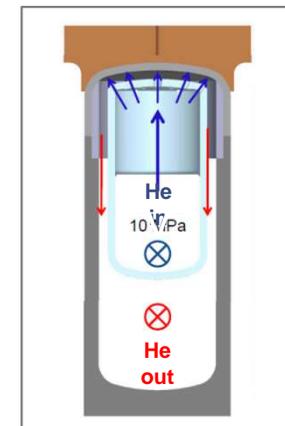
P. Norajitra et al. (2003-2009)

Pipe concept



Rieth, Reiser (2012)

Finger + Pipe

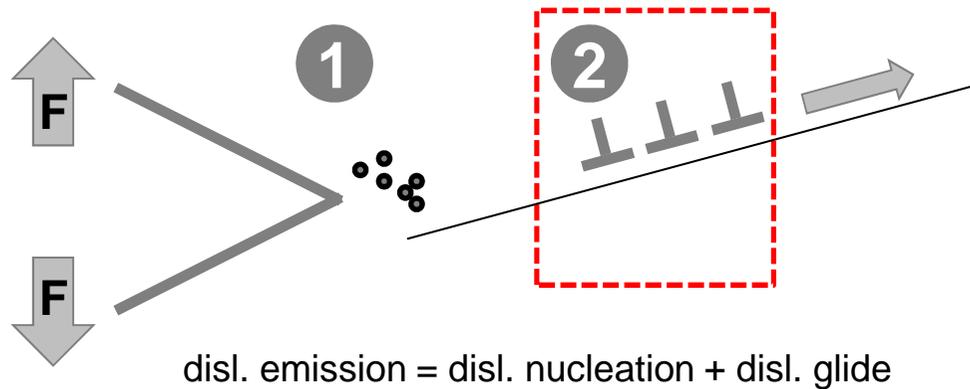


Malang, Tillack, ARIES team (2008-2011)

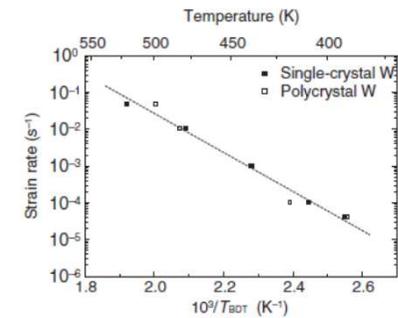
Contents

- Electrical industry
- Fusion applications
- **Ductilisation of tungsten (W)**
 - **Alloying, composite material, UFG**
 - W-foil (UFG) laminates
- W-laminates for high heat flux applications

What is/are the controlling factor/s of the BDT?

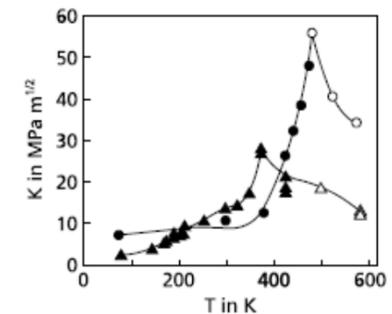


$$\dot{\epsilon} = A \exp\left(-\frac{\Delta H_{BDT}}{kT_{BDT}}\right)$$



Roberts (2007)

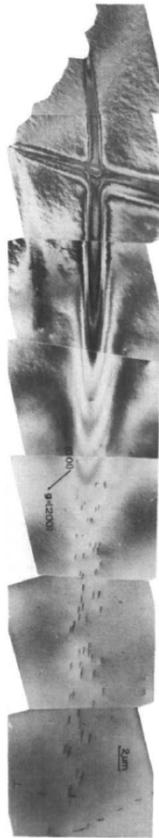
- T_{BDT} is strain rate dependent: $\Delta H_{BDT} = 1,05 \pm 0,05 \text{ eV} \sim \Delta H_{kp} > \Delta H_{edge}$
 → BDT mobility controlled
- pronounced influence of disl. sources on K
 → nucleation-controlled



Gumbsch (2003)

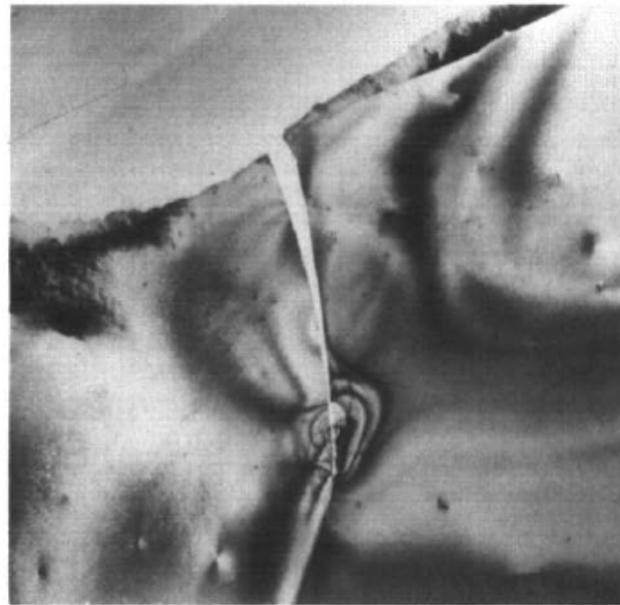
What is/are the controlling factor/s of the BDT?

Distribution of dislocations
ahead of crack tips in
tungsten single crystal



S.M. Ohr (1980)

polyc. W: grain boundary crack



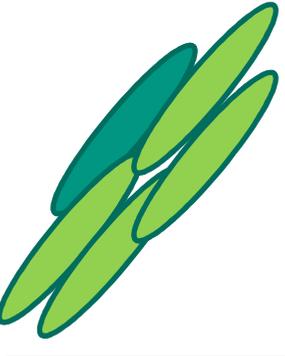
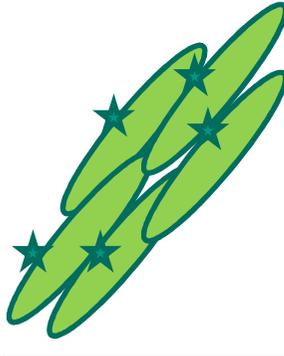
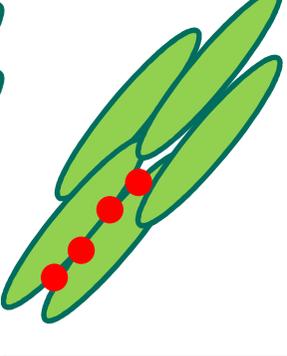
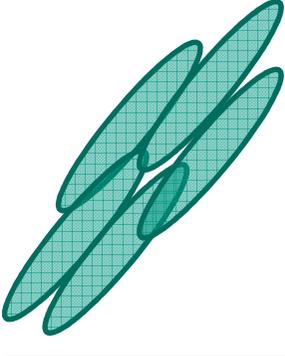
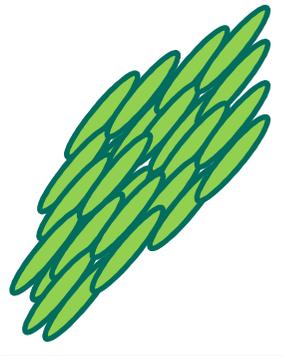
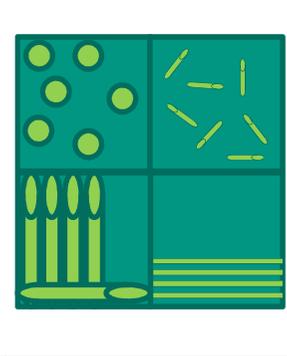
S.M. Ohr (1980)

W foil: in-situ TEM tensile test



M. Klimenkov, U. Jäntschi, KIT (2013)

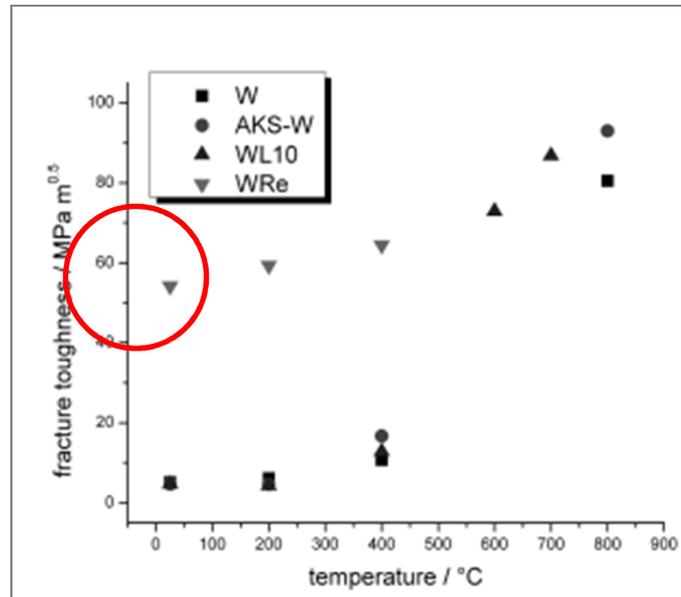
Ductilisation strategies

oxides	insoluble metals	roll of impurities	1. alloying	2. UFG	3. composite
					
oxides? <ul style="list-style-type: none"> • La_2O_3 (WL10) • Y_2O_3 	insoluble metals? <ul style="list-style-type: none"> • K (WVM) 	decrease of impurities?	WRe (WIr) is ductile <ul style="list-style-type: none"> • WTa • WV 	mass production <ul style="list-style-type: none"> • SPD • mech. alloying 	<ul style="list-style-type: none"> • particle • short fibre • long fibre • <u>laminate</u>

→ pure W is the best W (in terms of ductility measured by Charpy)

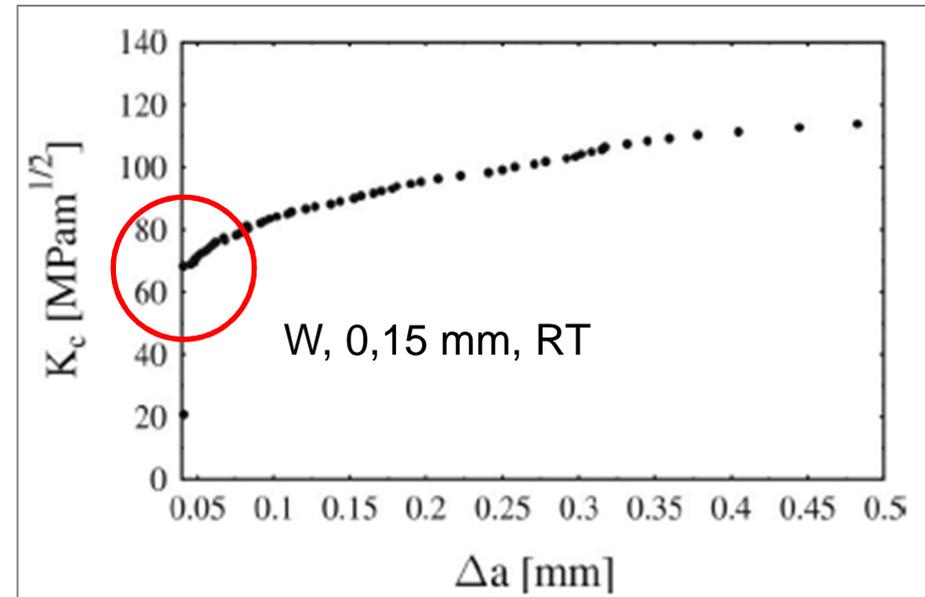
Ductilisation strategies

■ Alloying (WRe) vs. UFG



B. Gludovatz, ÖAW

K_Q , WRe26wt.%, rolled and stress relieved = 60 MPa(m)^{1/2} (at RT)

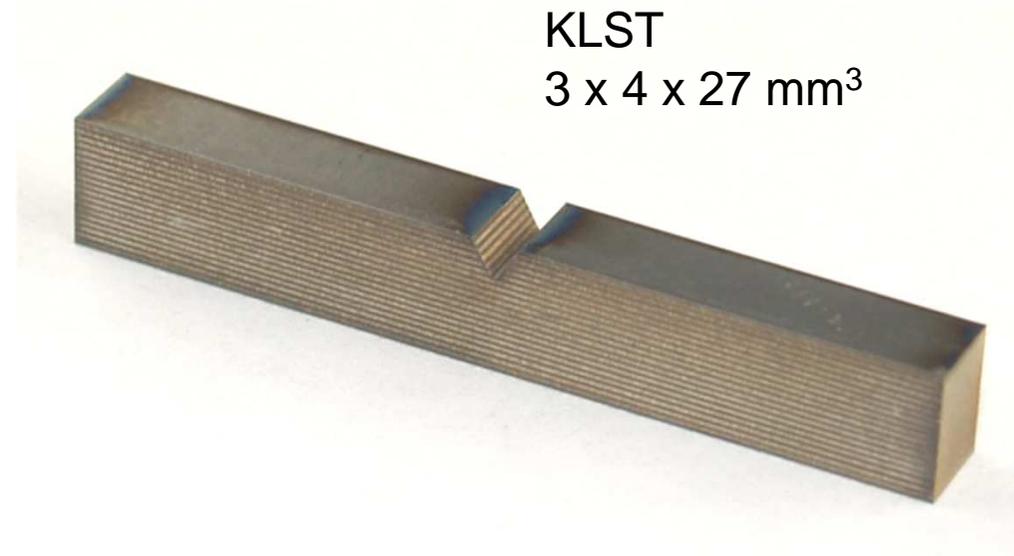
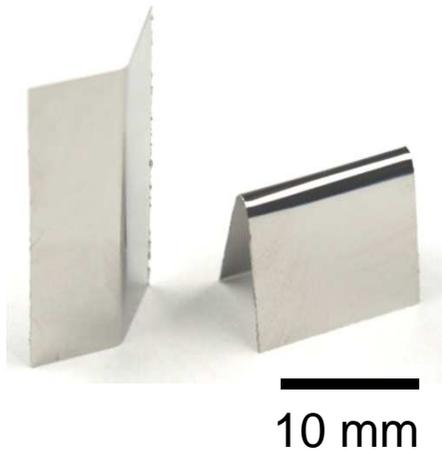


R. Pippen, ÖAW

K_Q , pure W foil, rolled

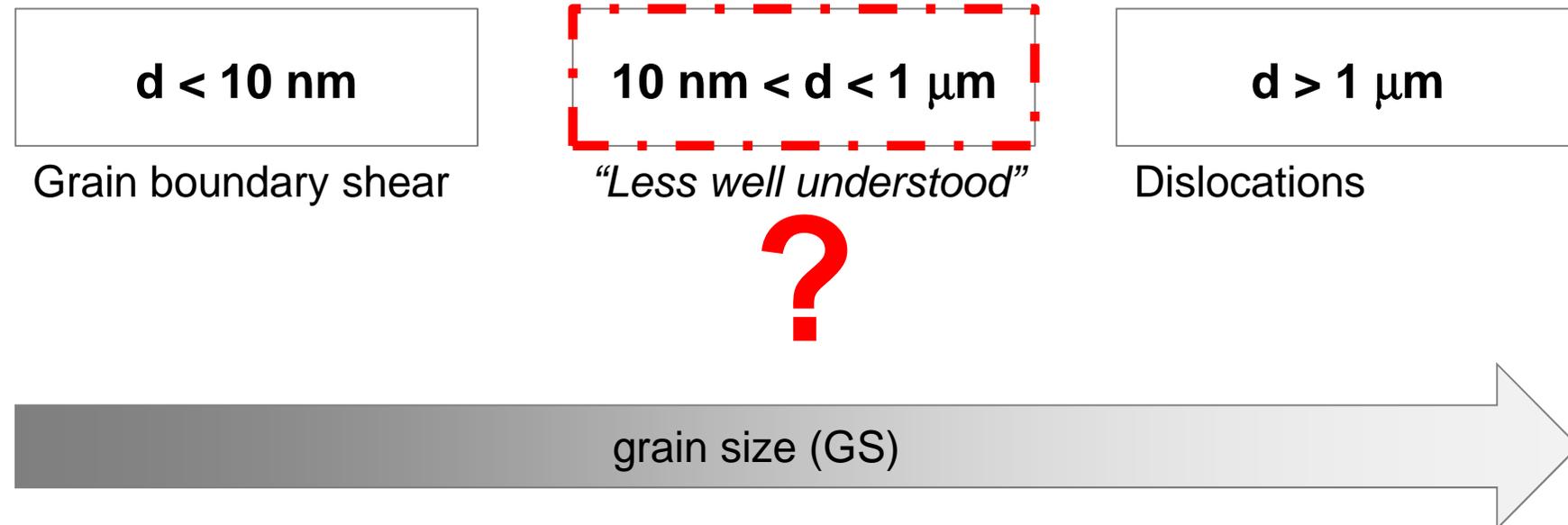
Our idea: W-laminates made of W-foil (UFG)

- Is it possible to expand the ductility and toughness of a W-foil (UFG) to the bulk?



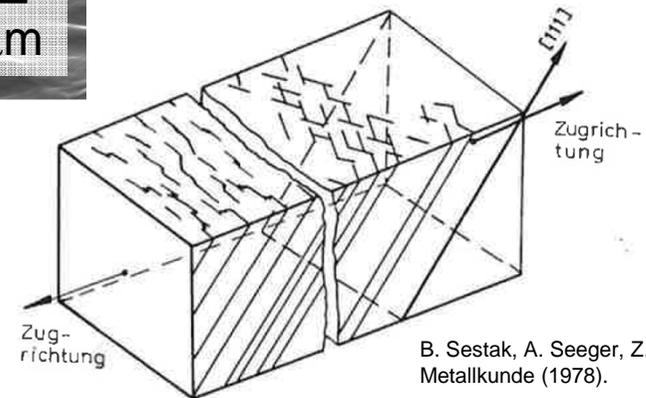
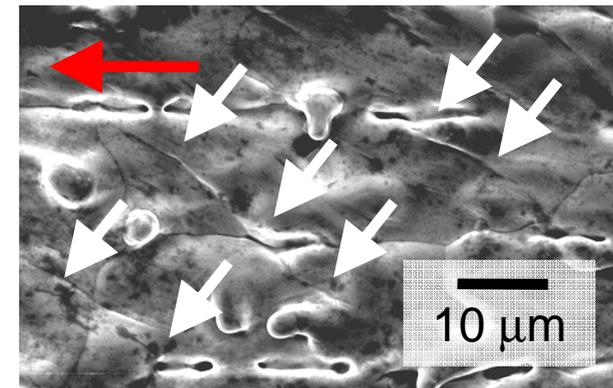
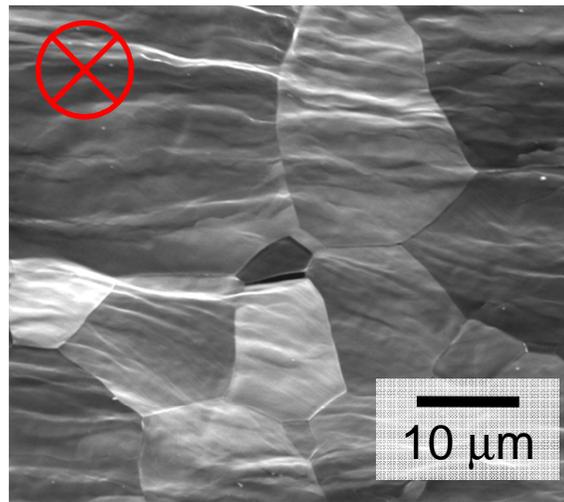
What is special about UFG?

- Which is the mechanism of deformation / plasticity?
- According to M.A. Meyers (2006): three regimes



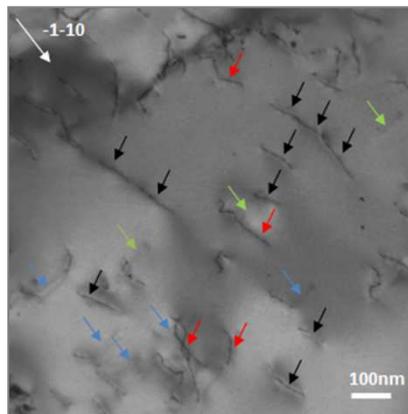
Mechanism of deformation of W-foil (UFG)?

- My personal assumptions: dislocation annihilation on the free surface
 - Slip direction: $\langle 111 \rangle$
 - Slip plane: $\{110\}$, $\{112\}$, $\{123\}$ → multiple cross slip

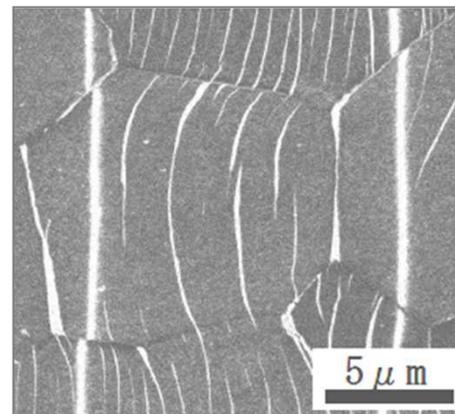


Mechanism of deformation of W-foil (UFG)?

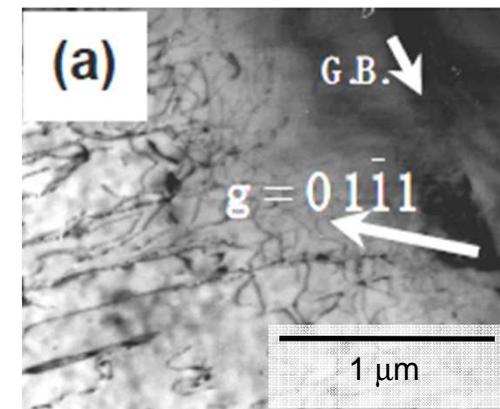
- My personal assumptions
 - Dislocation annihilation
 - High amount of mobile edge dislocations
 - Multiple slip at the GB
 - Grain rotation / grain boundary sliding
 - ...



Y. Xi, Oxford (2012)



J. Koike (2004)



J. Koike (2004)

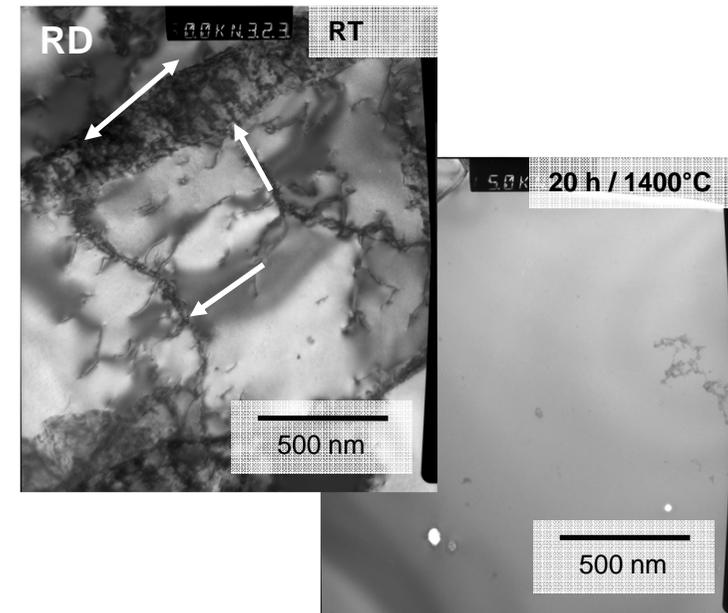
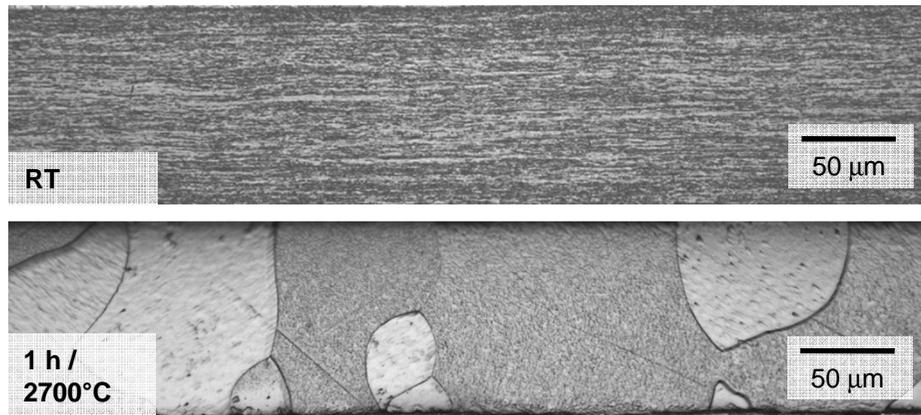
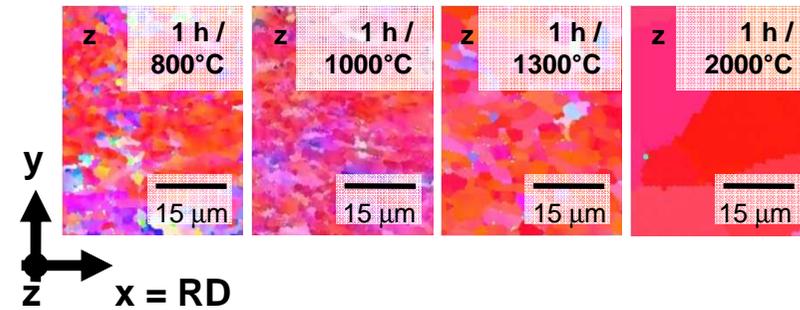
Contents

- Electrical industry
- Fusion applications
- **Ductilisation of tungsten (W)**
 - Alloying, composite material, UFG
 - **W-foil (UFG) laminates**
- W-laminates for high heat flux applications

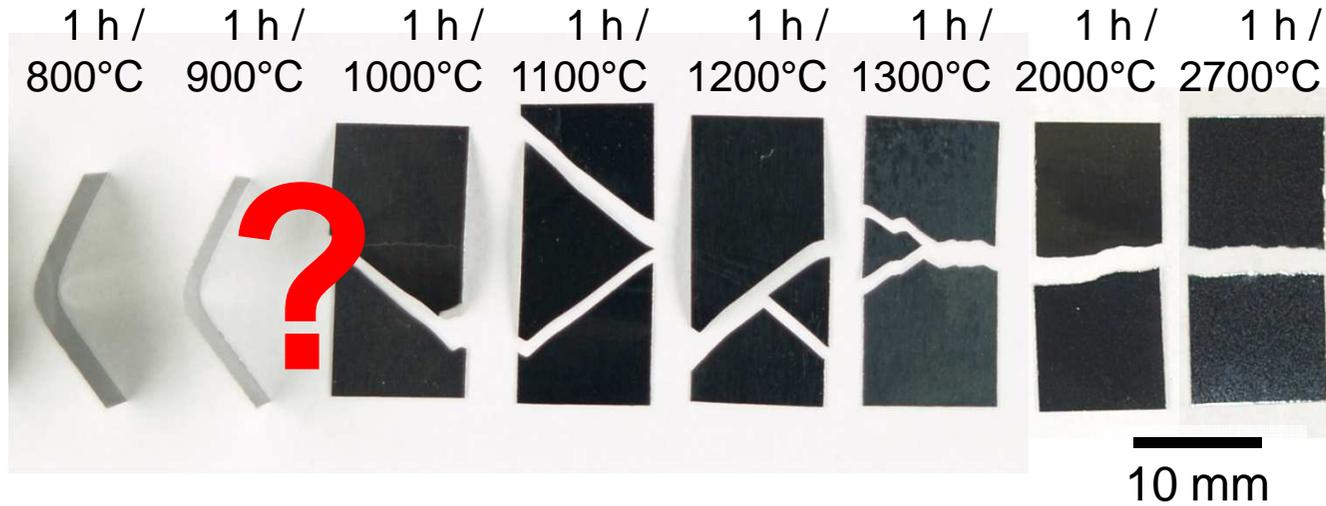
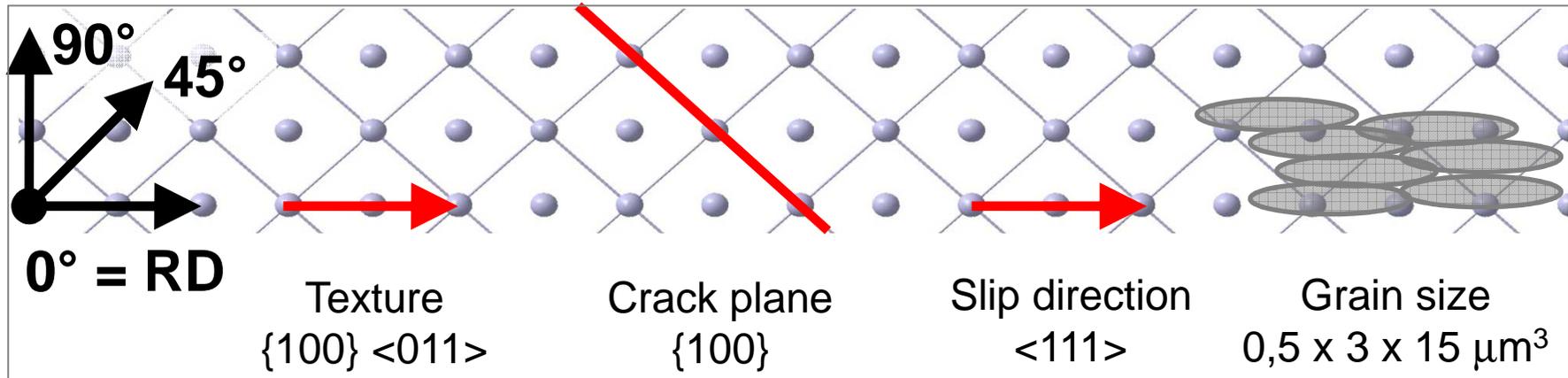
Microstructure of W-foil, 100 μm

- Grain size:
 - As-received: $0,5 \times 3 \times 15 \mu\text{m}^3$
 - 1 h / 2700°C: $100 \times 100 \times 100 \mu\text{m}^3$
- Texture: $\{100\} \langle 011 \rangle$; rotated cube
- Sub grains: nearly free from disl.
- Begin rxx: 1200°C

(pictures: J. Reiser, Y. Xiaou, D.E.J. Armstrong)

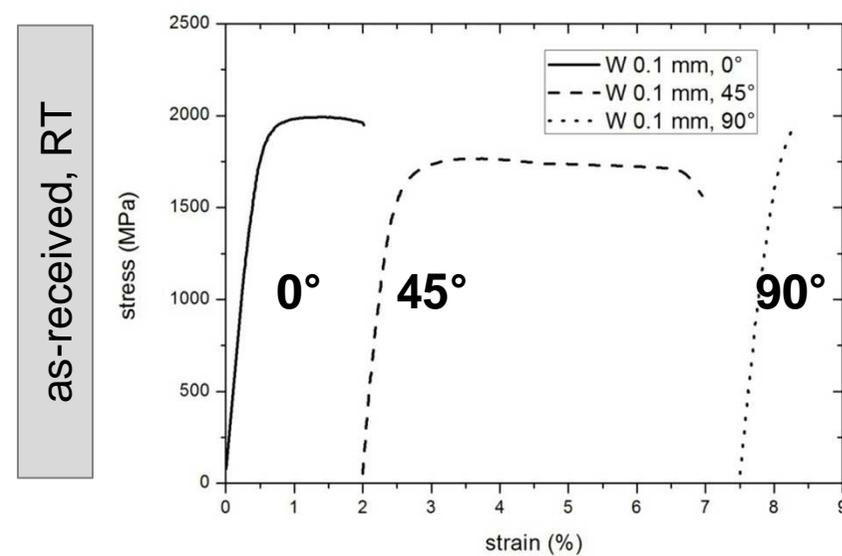
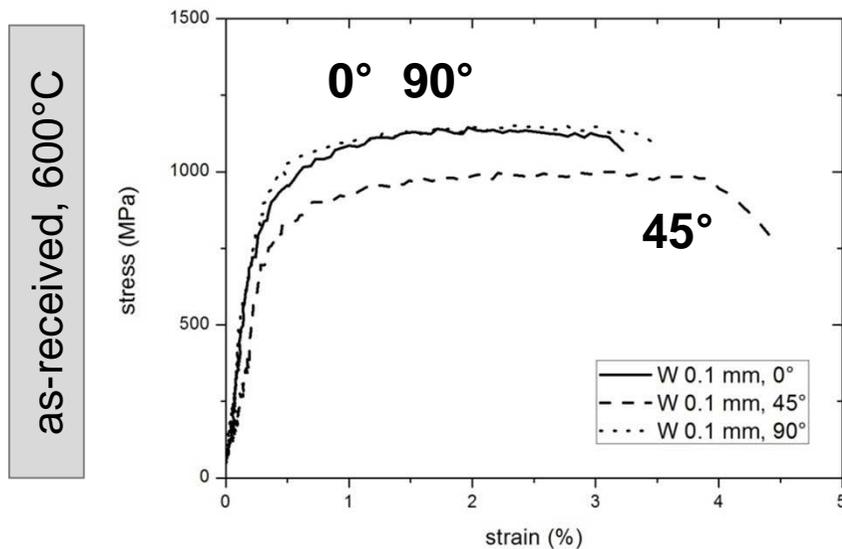
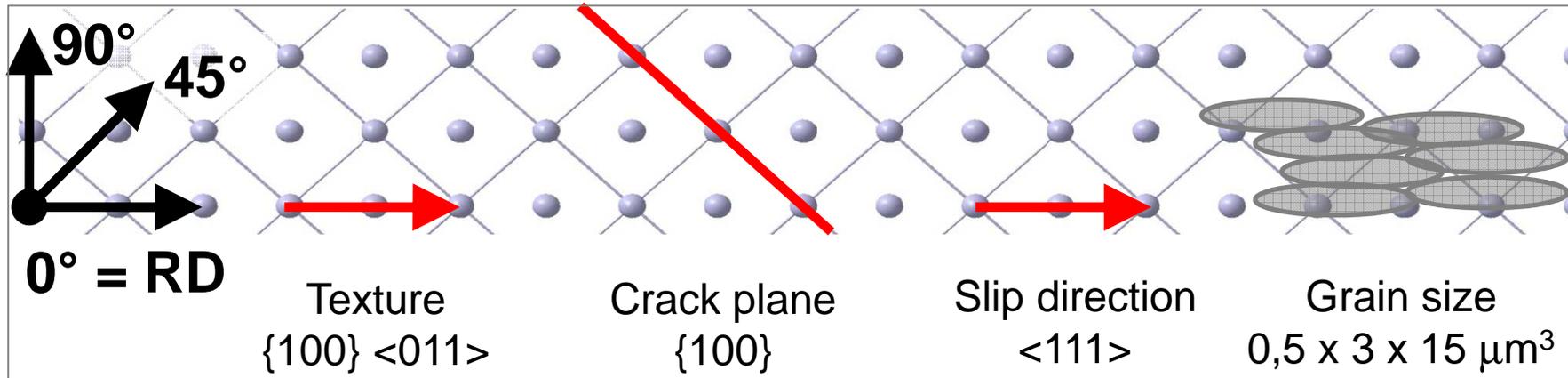


3PB-tests on W-foil, 100 μm



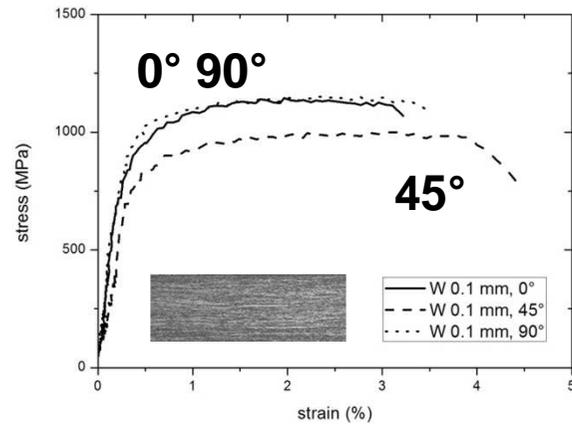
3 point bending test at RT

Tensile tests on W-foil, 100 μm



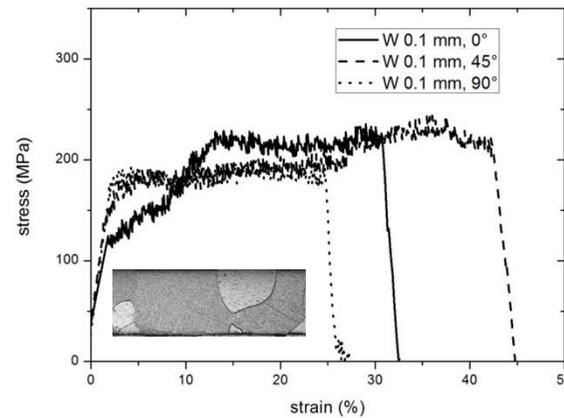
Tensile tests on W at 600°C

W0.1, as-received



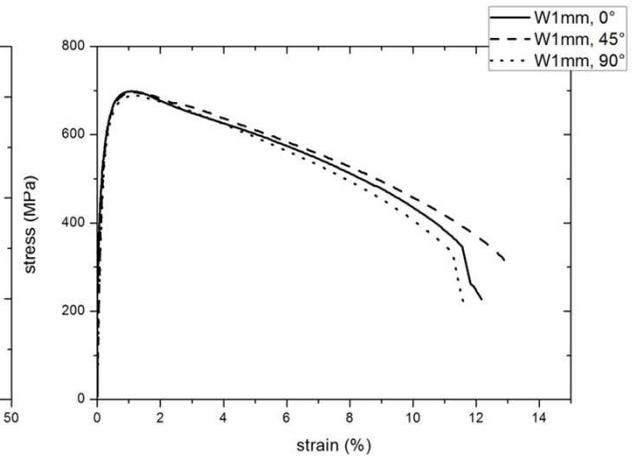
- no necking
- plasticity: homogeneous

W0.1, 1 h / 2000°C



- no necking
- plasticity: homogeneous

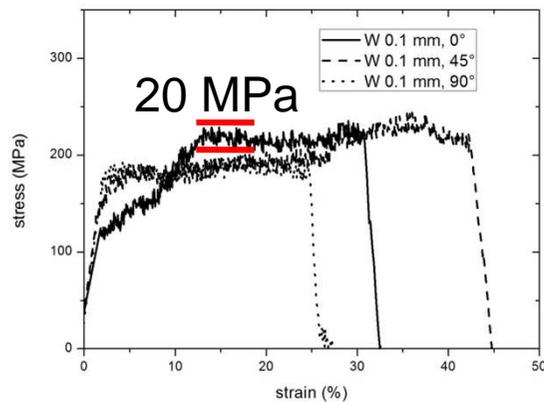
W1, as-received



- necking
- plasticity: localized

Tensile tests on W at 600°C

W0.1, 1 h / 2000°C



W SX [1]

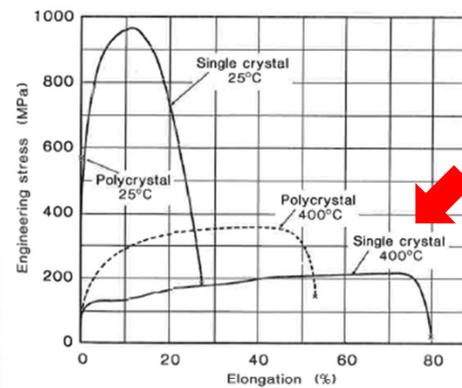


FIGURE 1.14. Stress-strain curves of polycrystal and single-crystal tungsten at 25°C and 400°C [1.52]; strain rate $2\% \cdot \text{min}^{-1}$

Mo SX, pre. def. [2]

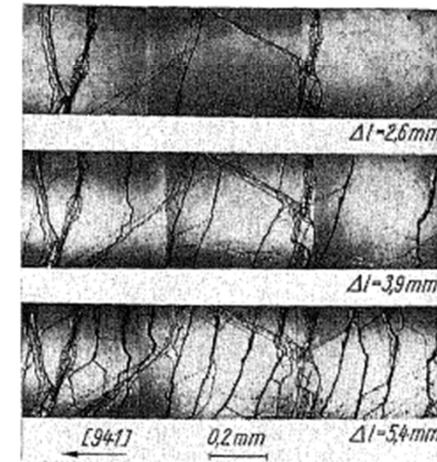
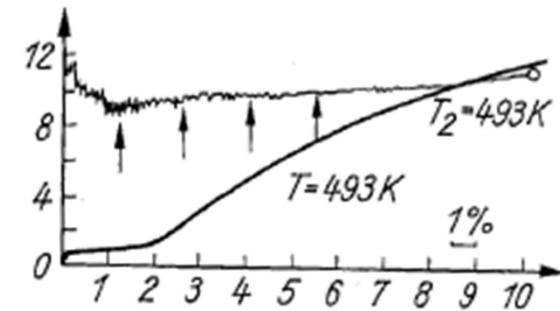


Fig. 3

- $20 \text{ MPa} \cdot 0.2 \text{ mm}^2 = 4 \text{ N}$
- Serrated flow, strain ageing, discontinuous slip (*Portevin-Le Chatelier-Effect PLC*)

Literature:

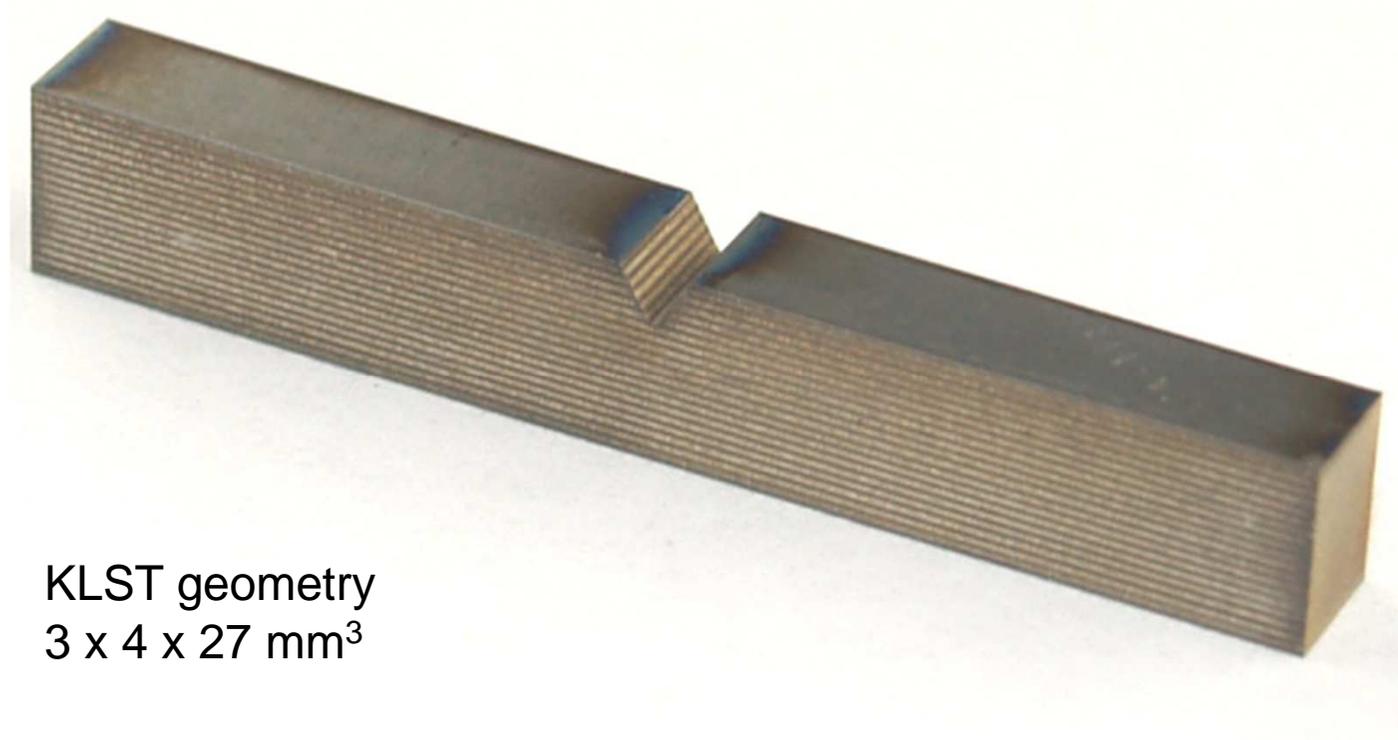
- [1] E. Lassner, W.-D. Schubert, *Tungsten* (1999) p. 25.
 [2] Ch. Ritches, A. Luft, D. Schulze, *Kristall und Technik*, **13**, 7 (1978) 791.

W-laminate: microstructure

The mechanical properties of a W-laminate depend on

- the condition of the W-foil as well as
- the interface

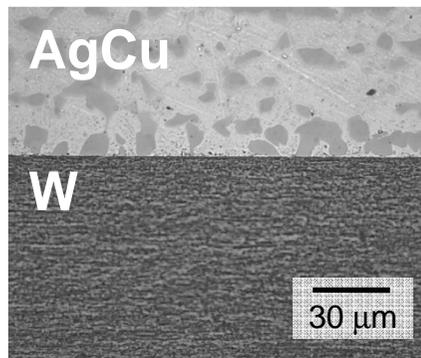
after the joining process.



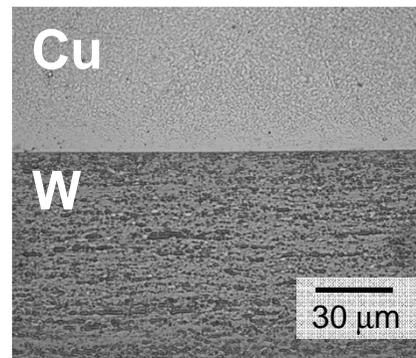
KLST geometry
 $3 \times 4 \times 27 \text{ mm}^3$

W-laminate: microstructure

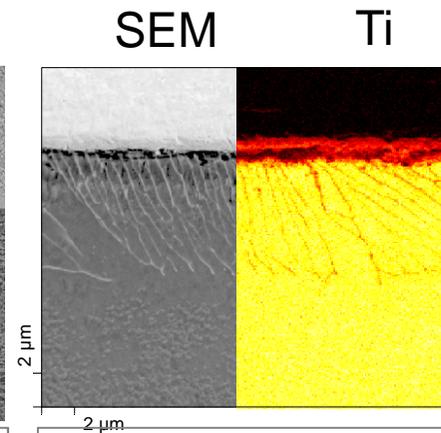
- Condition of the W-foil:
 - As-received
 - Recrystallized
- Condition of the interface:
 - Wettability
 - Solid solution
 - Intermetallic compounds



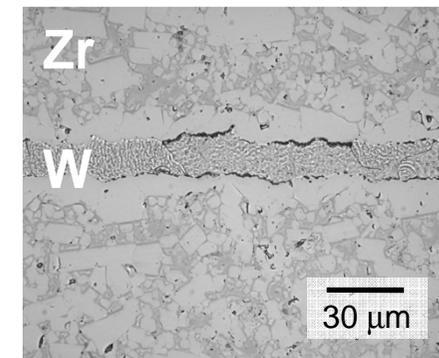
$$T_M^{\text{AgCu}} = 780^\circ\text{C}$$



$$T_M^{\text{Cu}} = 1085^\circ\text{C}$$



$$T_M^{\text{Ti}} = 1670^\circ\text{C}$$

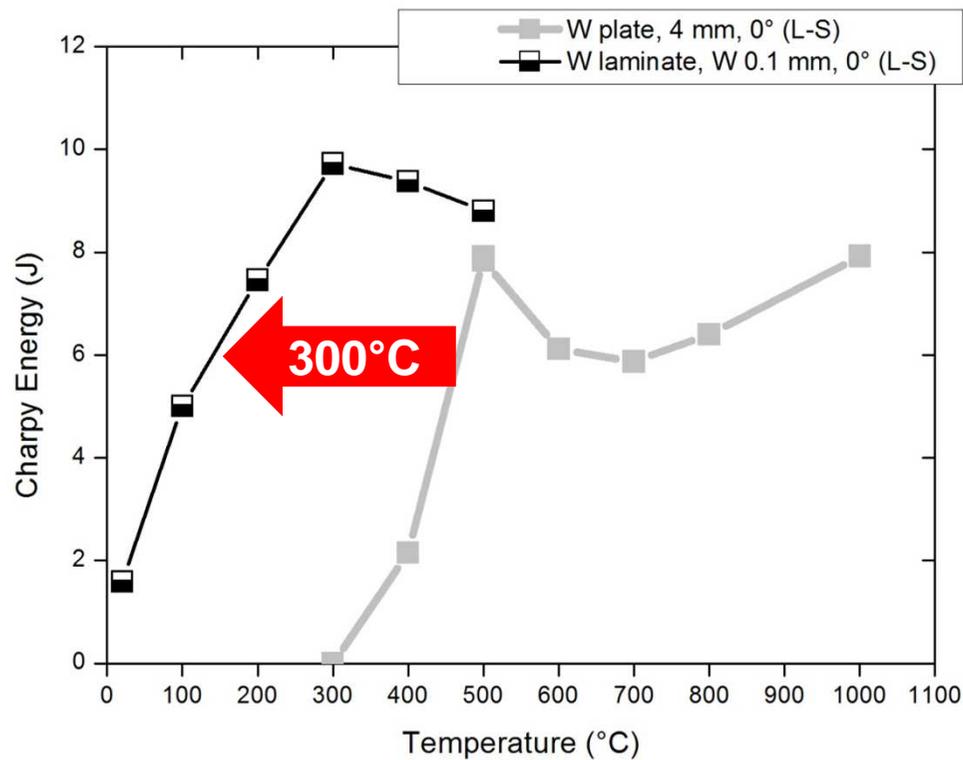


$$T_M^{\text{Zr}} = 1855^\circ\text{C}$$

T. Weingärtner, KIT (2013)

W-laminates: Charpy impact tests

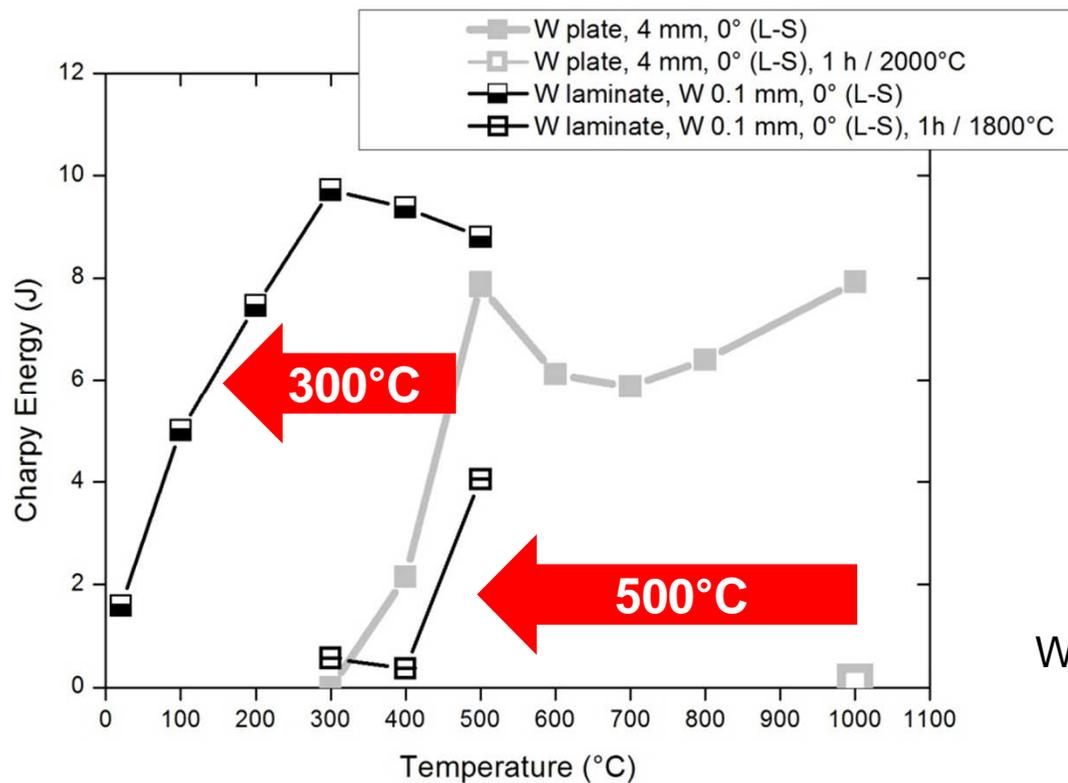
- Can the ductile properties of a W-foil be transferred to the bulk?
 - As-received: improvement of 300°C



W-laminate made of Cu alloy

W-laminates: Charpy impact tests

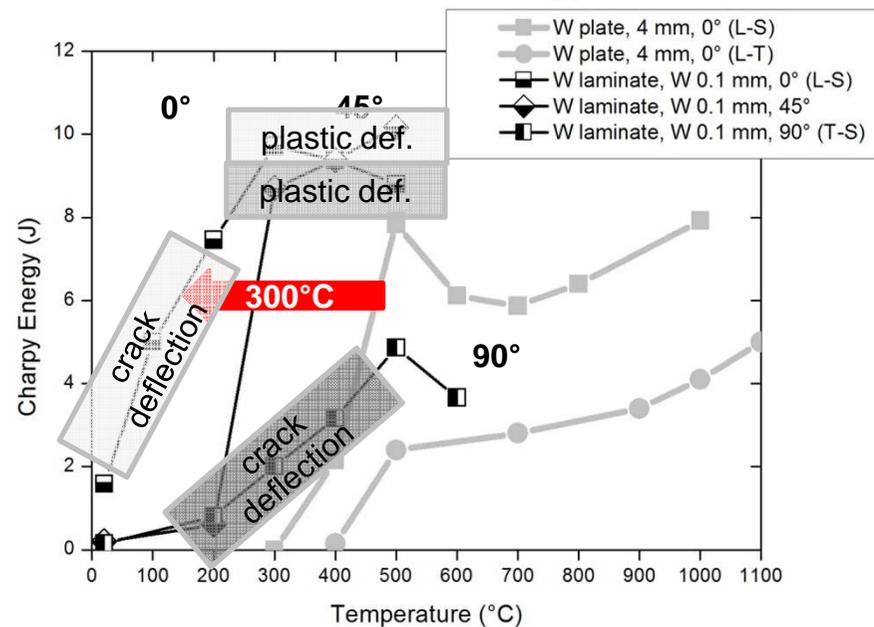
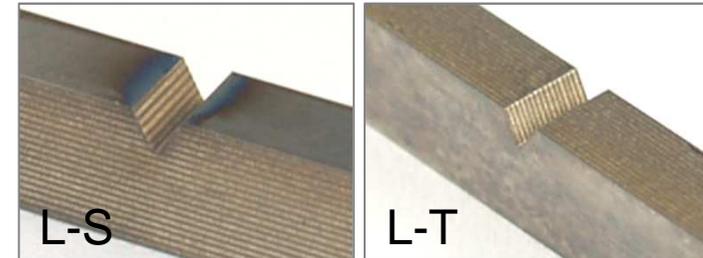
- Can the ductile properties of a W-foil be transferred to the bulk?
 - As-received: improvement of 300°C
 - Recrystallized: improvement of 500°C



W-laminate made of Cu alloy

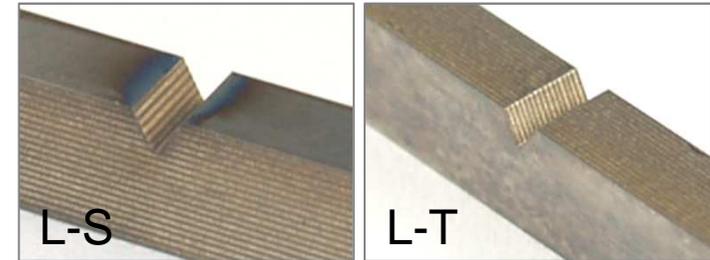
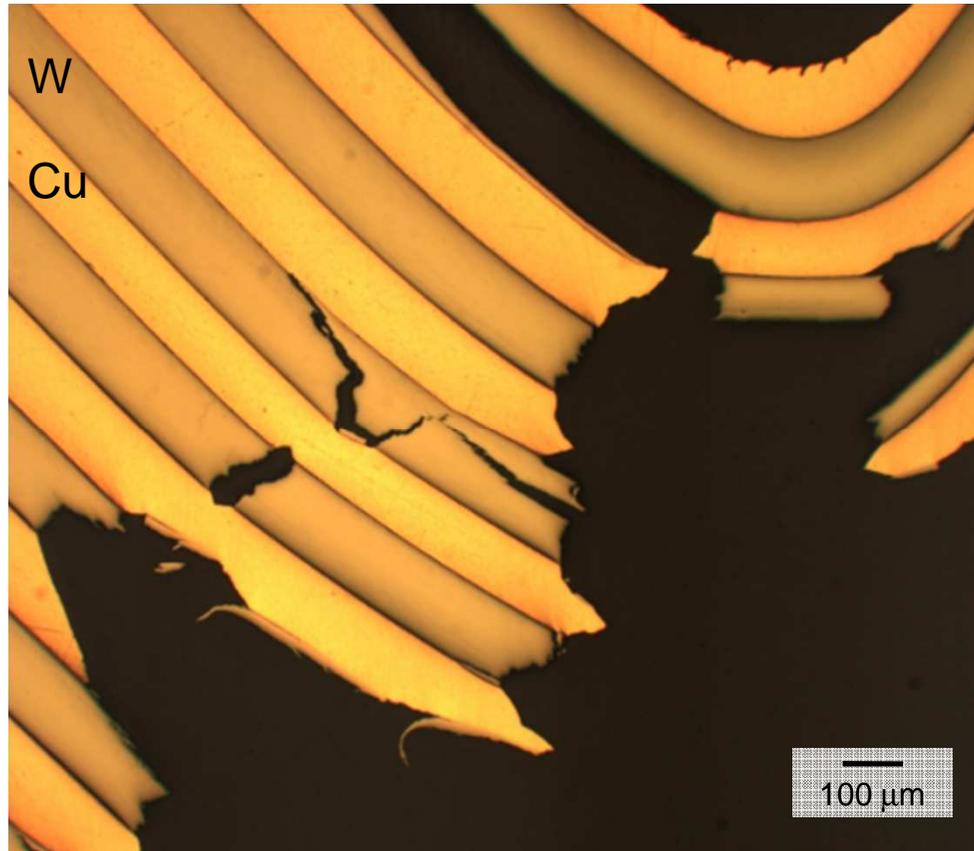
W-laminates: energy dissipation

- How do laminates dissipate energy?
 - 1) Pl. deformation of the W-foil
 - 2) Pl. deformation of the interlayer
 - 3) Creation of surface by crack deflection
→ non-plastic energy dissipation



W-laminates: crack behavior

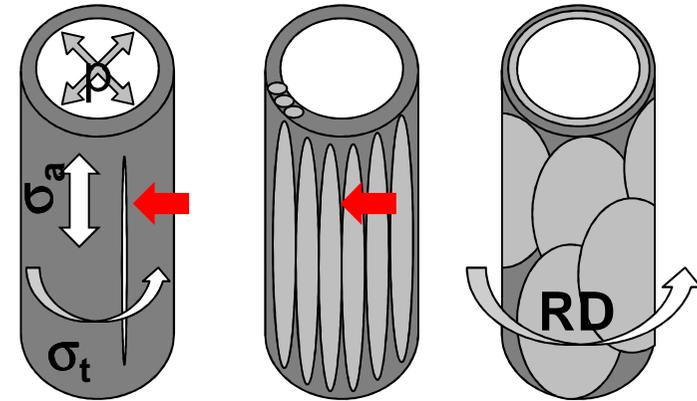
- How does the crack path look like?



W-laminate, WCu, L-S, RT

W-laminates: pipes

- How can a tungsten pipe be produced?
 - Extrusion → very challenging
 - Drilling a hole in a rod
 - **NEW: by rolling up a W-foil**



15 mm

rod



AgCu, 780°C



Cu, 1085°C



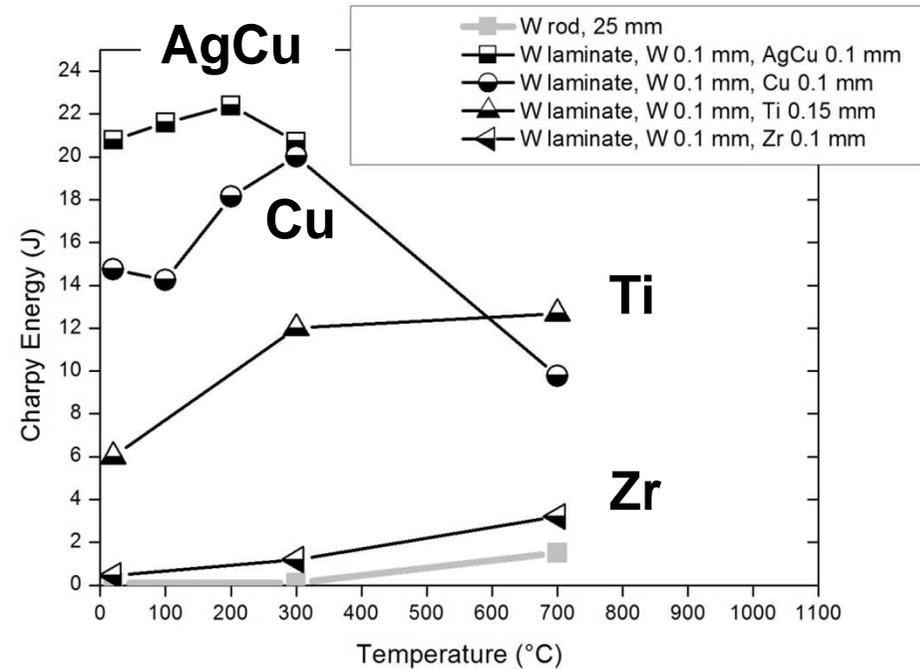
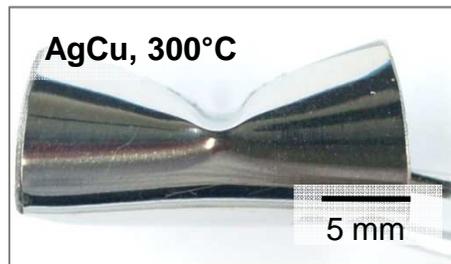
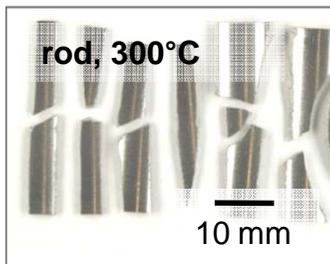
Ti, 1670°C



Zr, 1855°C

W-laminates: pipes

- Characterization by
 - Charpy impact tests
 - Burst test

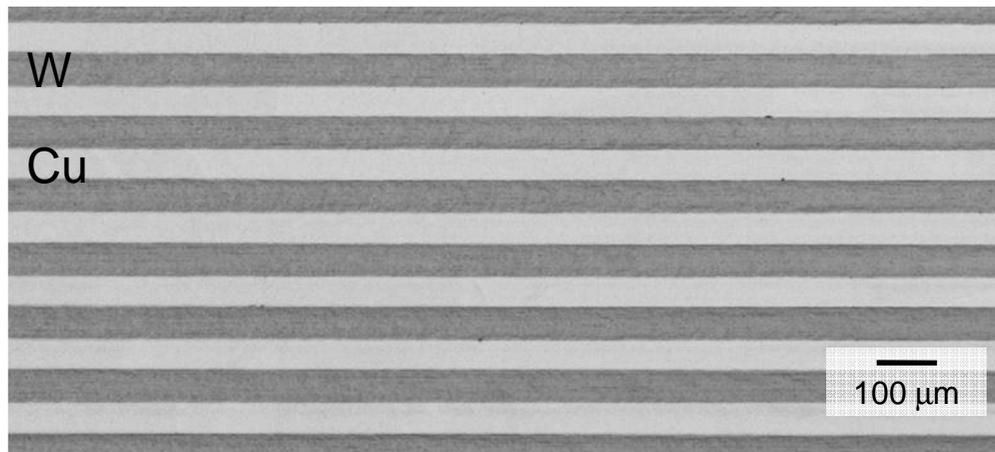


Contents

- Electrical industry
- Fusion applications
- Ductilisation of tungsten (W)
 - Alloying, composite material, UFG
 - W-foil (UFG) laminates
- **W-laminates for high heat flux applications**

W-laminates for high heat flux applications

- Electrical industry – fusion application → Mo/W-laminates
 - Cu: high thermal conductivity, k ; Mo: low coefficient of thermal expansion, α
 - High toughness, K_Q , and ductility



Electrical ind.



PLANSEE SE

W-laminates for high heat flux applications

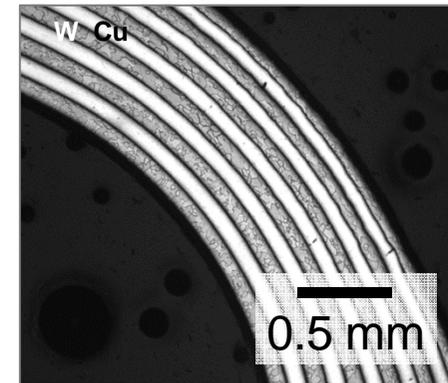
- W-laminates for water- and helium-cooled divertors



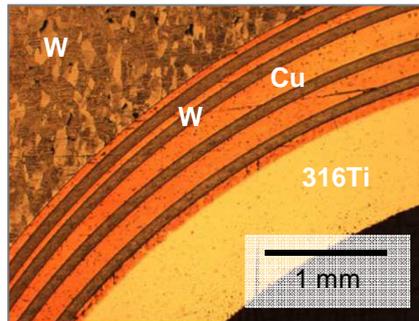
Thible for HEMJ



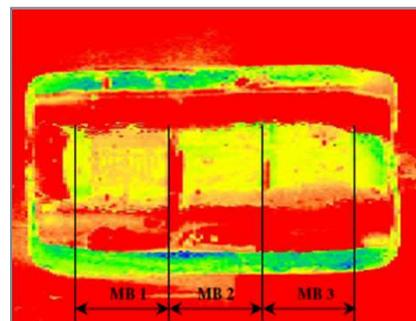
W-laminate



microstructure



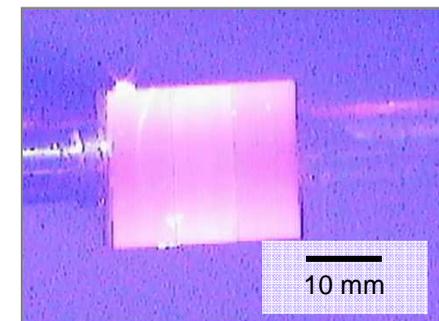
W-laminate as interlayer



T. Huber, A. Zabernig
PLANSEE, NDT by ultrasonic

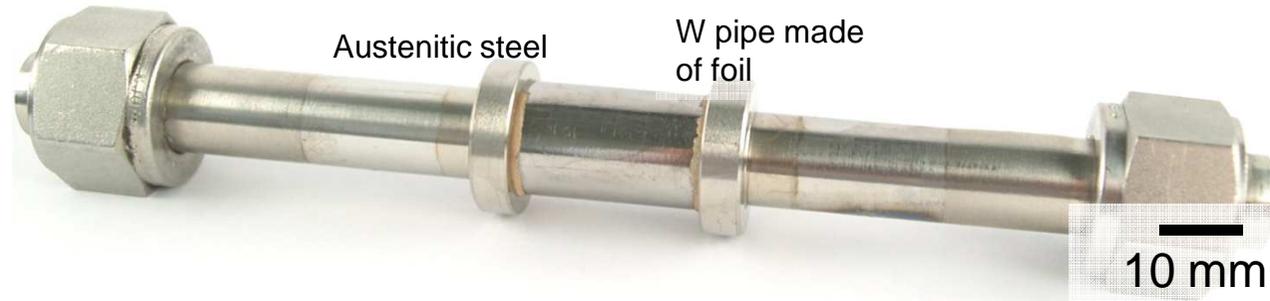


H. Greuner, B. Boeswirth
GLADIS, IPP, Garching



H. Greuner, B. Boeswirth
Test: 100 Zyklen, 6 MW/m²

W-laminates for high heat flux applications



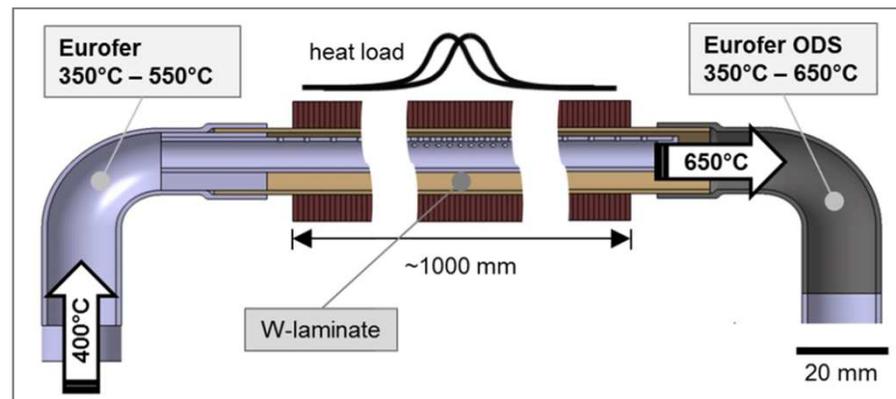
Burst test, RT, 1000 bar (in cooperation with PLANSEE SE, T. Huber, A. Zabernig)

Solar tower



ABENGOA Solar

He-cooled divertor, pipe concept



I will not spend 1 000 000 € for the one that...

- ... finds the controlling mechanism of the BDT.
- ... explains the deformation mechanism of W UFG.

“The intermediate grain size regime (10 nm – 1 μm) **is less well understood.**”

M.A. Meyers (2006)

W single crystal:

“The understanding of slightly more complicated microstructures and particularly of pre-deformed single crystals and/or textured and possibly pre-deformed polycrystalline materials **is far less well understood.**”

P. Gumbsch (2003)

Thank you for your attention

The authors are grateful to:

PLANSEE SE,
University of Oxford,
EFDA and
our colleagues from IAM (KIT).

